

Richieste CSN1 - 2015: ATLAS + 1/2 COMMON (no travel/metabolismo)

Attività	Descrizione	BO	CS	GE	MI	TN	UD	Nota
3D.1	6" Wafer procurement (SOI, wafer bonding, epi)	k€ -	k€ -	k€ -	k€ -	k€ 10.0	k€ -	Substrates for 2nd 3D batch (batch 5)
3D.2	PicoScope 6407 Digitizer with 1.5 GHz probes and accessories.	k€ -	k€ -	k€ -	k€ -	k€ 8.5	k€ -	Dynamic test on 3D structures for comparison with TCAD
BB.1	6" dummy wafers - test deposition on 6" and high-density bumps (150 k-bumps/chip)	k€ -	k€ -	k€ -	k€ 20.0	k€ -	k€ -	6k€ for dummy wafer with resistive chains, mask for In deposition, bump deposition (3W).
BB.2	BB for 3D sensor test	k€ -	k€ -	k€ 24.0	k€ -	k€ -	k€ -	To be done at Selex or IZM, when FBK 3D
MOD.1	Upgarde R/O Systems	k€ -	k€ 2.0	k€ 2.0	k€ 2.0	k€ -	k€ 2.0	USBpix3 + HV-CMOS R/O - 3 units
MOD.2	Module assembly and irradiation, RD on flex	k€ -	k€ -	k€ 10.0	k€ -	k€ -	k€ -	FlexHybrids and PCB for module test. Flex RD.
M-R/O	Multi module R/O	k€ 15.0	k€ -	k€ -	k€ -	k€ -	k€ -	Prototype boards, componets
CO2/μCH.1	Develop μ-channel cooling	k€ -	k€ -	k€ -	k€ 10.0	k€ -	k€ -	μ-channel demonstrator
Total requested by ATLAS		k€ 15.0	k€ 2.0	k€ 36.0	k€ 32.0	k€ 18.5	k€ 2.0	

Travel (test-beam)

Bologna	k€ 15.0	k€ -
Cosenza	k€ 2.0	k€ -
Genova	k€ 36.0	k€ -
Milano	k€ 32.0	k€ -
Trento	k€ 18.5	k€ 4.0
Udine	k€ 2.0	k€ -
k€ 105.5		

Spending profile - May 2014

	2015	Cut 2014
ATLAS (excluded HV-CMOS)	k€ 55.0	k€ 16.0
CMS	k€ 101.0	k€ 16.0
COMMON	k€ 68.0	

Total: ATLAS 2015 + Cut 2014 + 1/2 COMMON **k€ 105.0**